

ABSTRACT

ELECTRICALLY CONDUCTIVE PASTE AND SEMICONDUCTOR DEVICE PREPARED BY USING THE PASTE

An electrically conductive paste comprises 80% by weight or more of silver powder and 20% by weight or less of a thermosetting resin. The silver powder has a particle size distribution having two peaks at specific positions. Viscosities of the paste measured under a low shearing stress and under a high shearing stress are in respective specific ranges and the ratio of these viscosities is in a specific range. A cured product obtained by heating the paste has a tensile modulus in a specific range. The paste has thermal and electric conductivities approximately the same as those of solder, shows little change in properties under a high temperature and a high humidity or under cyclic cooling and heating, exhibits excellent workability in coating and can be applied to coating by using nozzles having a wide range of diameters. A reliable semiconductor device is prepared by using the paste.

FIGURE : NONE



162162



G00002